Power MOSFET

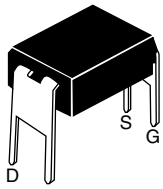
PRODUCT SUMMARY		
V_{DS} (V)	-60	
$R_{DS(on)}$ (Ω)	V_{GS} = -10 V	0.10
Q_g max. (nC)	19	
Q_{gs} (nC)	5.4	
Q_{gd} (nC)	11	
Configuration	Single	

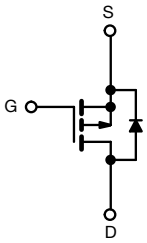
FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- For automatic insertion
- End stackable
- P-channel
- 175 °C operating temperature
- Fast switching

RoHS COMPLIANT

HVMDIP





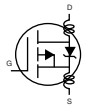
P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	-60	V
Gate-Source Voltage			V_{GS}	± 20	
Continuous Drain Current	V_{GS} at -10 V	T_A = 25 °C	I_D	-3.0	A
		T_A = 100 °C		-2.1	
Pulsed Drain Current [a]			I_{DM}	-15	
Linear Derating Factor				0.0083	W/°C
Single Pulse Avalanche Energy [b]			E_{AS}	180	mJ
Repetitive Avalanche Current [a]			I_{AR}	-3.0	A
Repetitive Avalanche Energy [a]			E_{AR}	0.23	mJ
Maximum Power Dissipation	T_A = 25 °C		P_D	2.3	W
Peak Diode Recovery dV/dt [c]			dV/dt	-4.5	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	-55 to +175	°C
Soldering Recommendations (Peak temperature) [d]	For 10 s			300	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. V_{DD} = -25 V, starting T_J = 25 °C, L = 15 mH, R_g = 25 Ω, I_{AS} = -3.2 A (see fig. 12).
c. I_{SD} ≤ -11 A, dI/dt ≤ -140 A/ms, V_{DD} ≤ V_{DS}, T_J ≤ 175 °C.
d. 1.6 mm from case.

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum Junction-to-Ambient	R_{thJA}	-	120	°C/W

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = - 250 µA		-60	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = -1 mA		-	- 0.056	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = -1 µA		-2.0	-	-4.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 20		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = -60 V, V_{GS} = 0 V		-	-	- 100	µA
		V_{DS} = -48 V, V_{GS} = 0 V, T_J = 150 °C		-	-	- 500	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = -10 V	I_D = - 0.96 A [b]	-	0.10	-	Ω
Forward Transconductance	g_{fs}	V_{DS} = -25 V, I_D = - 0.96 A [b]		1.3	-	-	S
Dynamic							
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = -25 V, f = 1.0 MHz, see fig. 5		-	570	-	pF
Output Capacitance	C_{oss}			-	360	-	
Reverse Transfer Capacitance	C_{rss}			-	65	-	
Total Gate Charge	Q_g	V_{GS} = -10 V	I_D = - 11 A, V_{DS} = -48 V, see fig. 6 and 13 [b]	-	-	19	nC
Gate-Source Charge	Q_{gs}			-	-	5.4	
Gate-Drain Charge	Q_{gd}			-	-	11	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = - 30 V, I_D = -11 A, R_g = 18 Ω, R_D = 2.5 Ω, see fig. 10[b]		-	13	-	ns
Rise Time	t_r			-	68	-	
Turn-Off Delay Time	$t_{d(off)}$			-	15	-	
Fall Time	t_f			-	29	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.0	-	nH
Internal Source Inductance	L_S			-	6.0	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	- 1.6	A
Pulsed Diode Forward Current [a]	I_{SM}			-	-	- 13	
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = -1.6 A, V_{GS} = 0 V [b]		-	-	- 6.3	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = - 11A, di/dt = 100 A/µs [b]		-	100	200	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	0.32	0.64	µC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

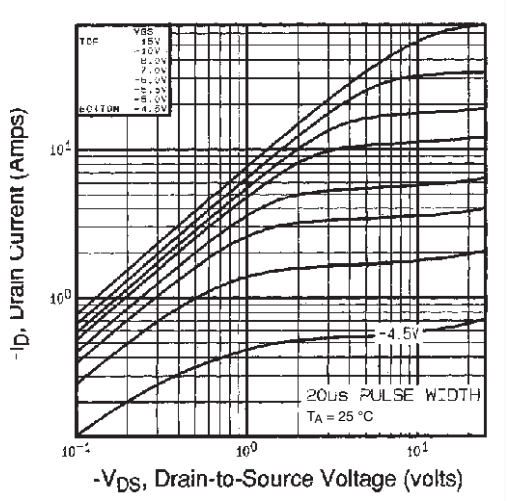


Fig. 1 - Typical Output Characteristics, T_A = 25 °C

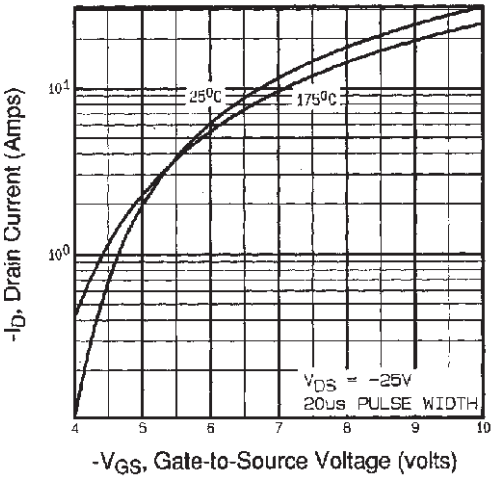


Fig. 3 - Typical Transfer Characteristics

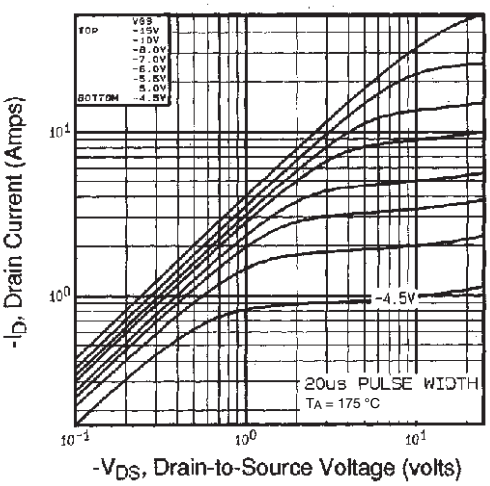


Fig. 2 - Typical Output Characteristics, T_A = 175 °C

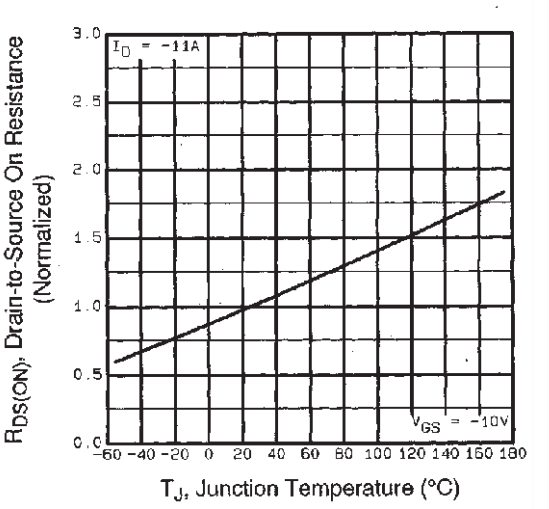


Fig. 4 - Normalized On-Resistance vs. Temperature

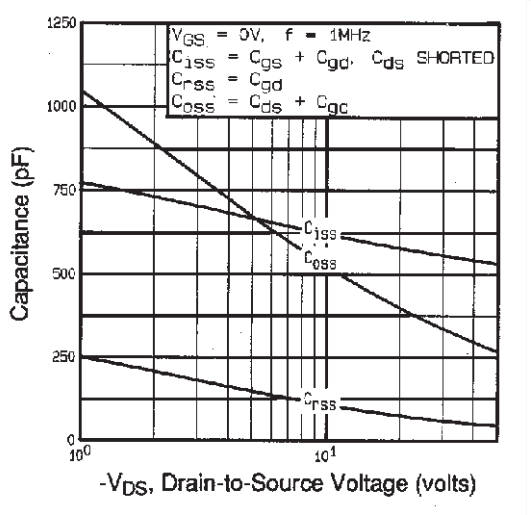


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

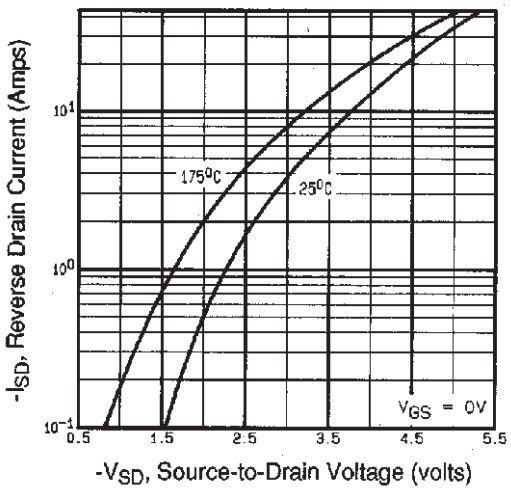


Fig. 7 - Typical Source-Drain Diode Forward Voltage

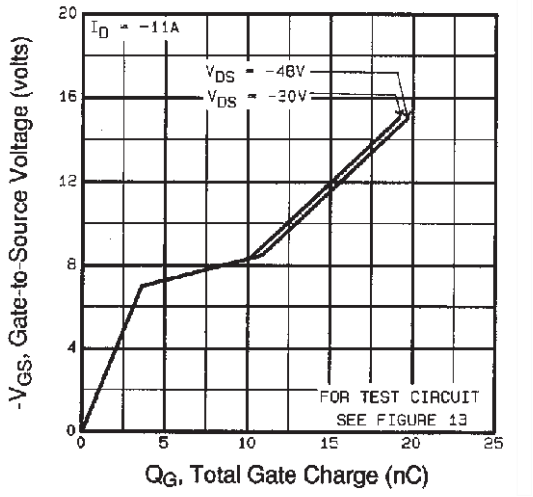


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

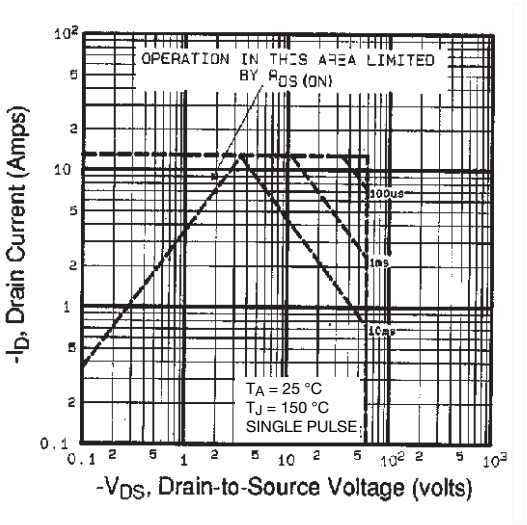


Fig. 8 - Maximum Safe Operating Area

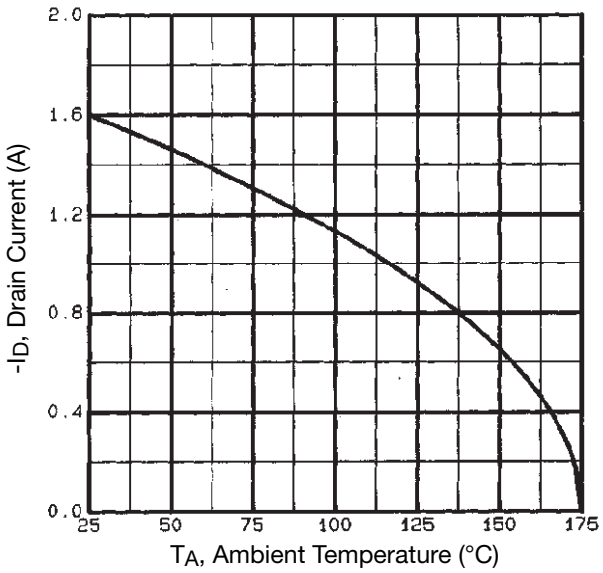


Fig. 9 - Maximum Drain Current vs. Ambient Temperature

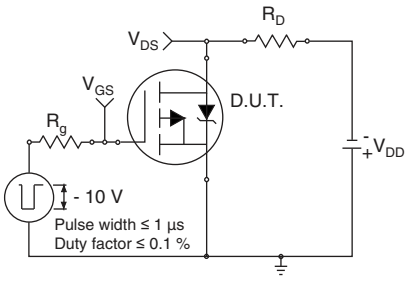


Fig. 10a - Switching Time Test Circuit

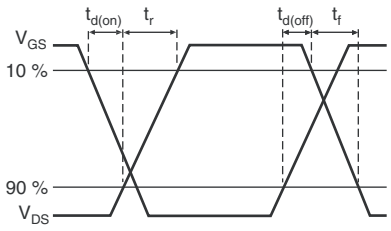


Fig. 10b - Switching Time Waveforms

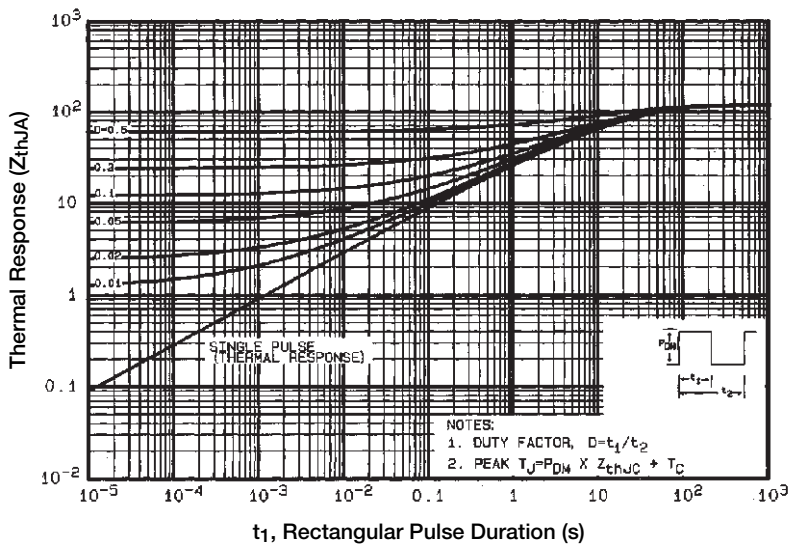


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

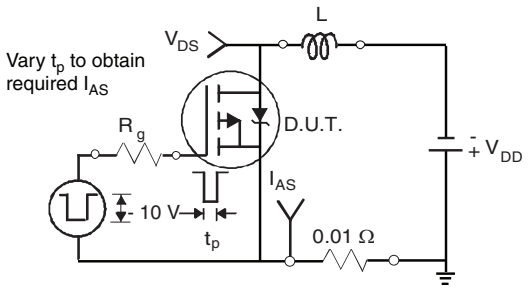


Fig. 12a - Unclamped Inductive Test Circuit

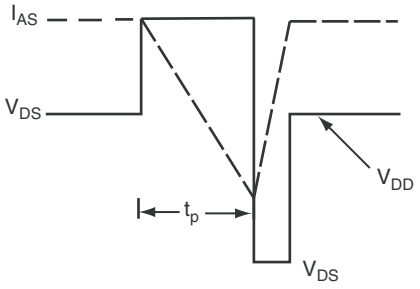


Fig. 12b - Unclamped Inductive Waveforms

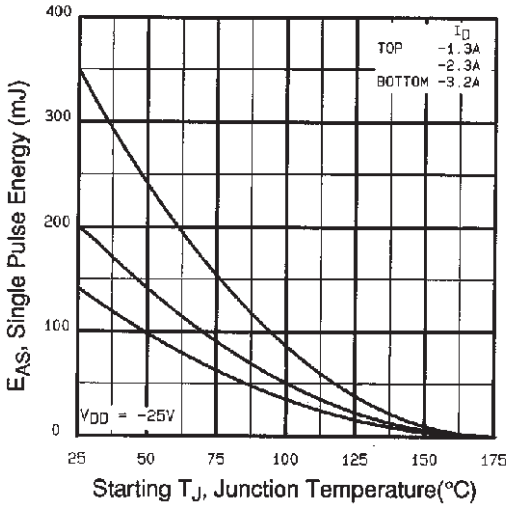


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

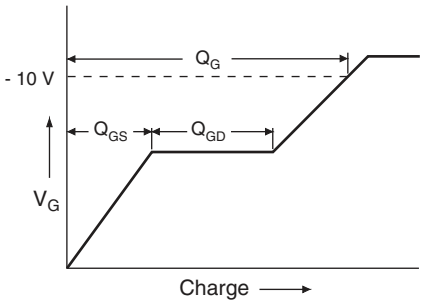


Fig. 13a - Basic Gate Charge Waveform

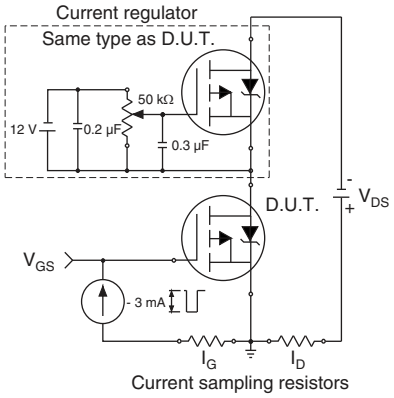
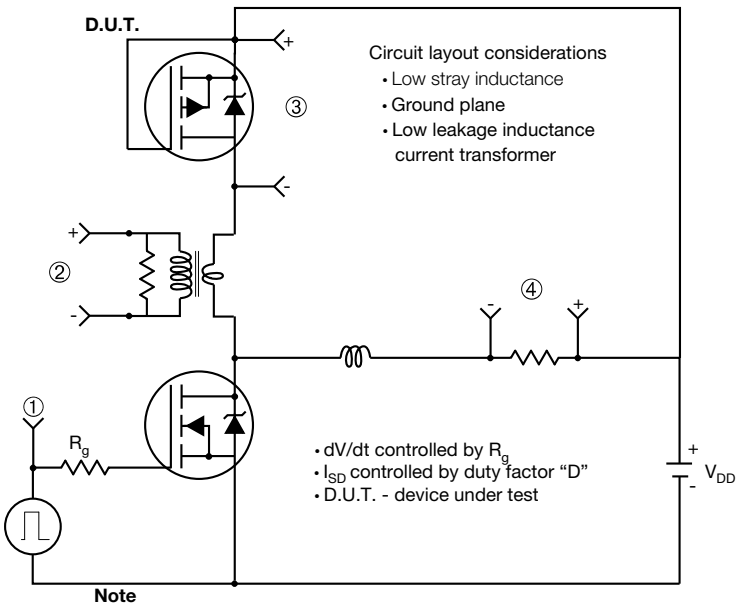
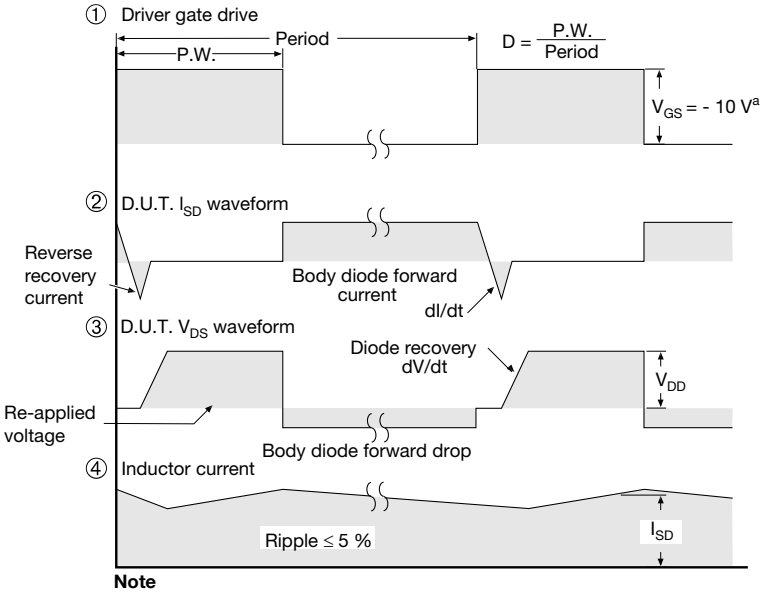


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



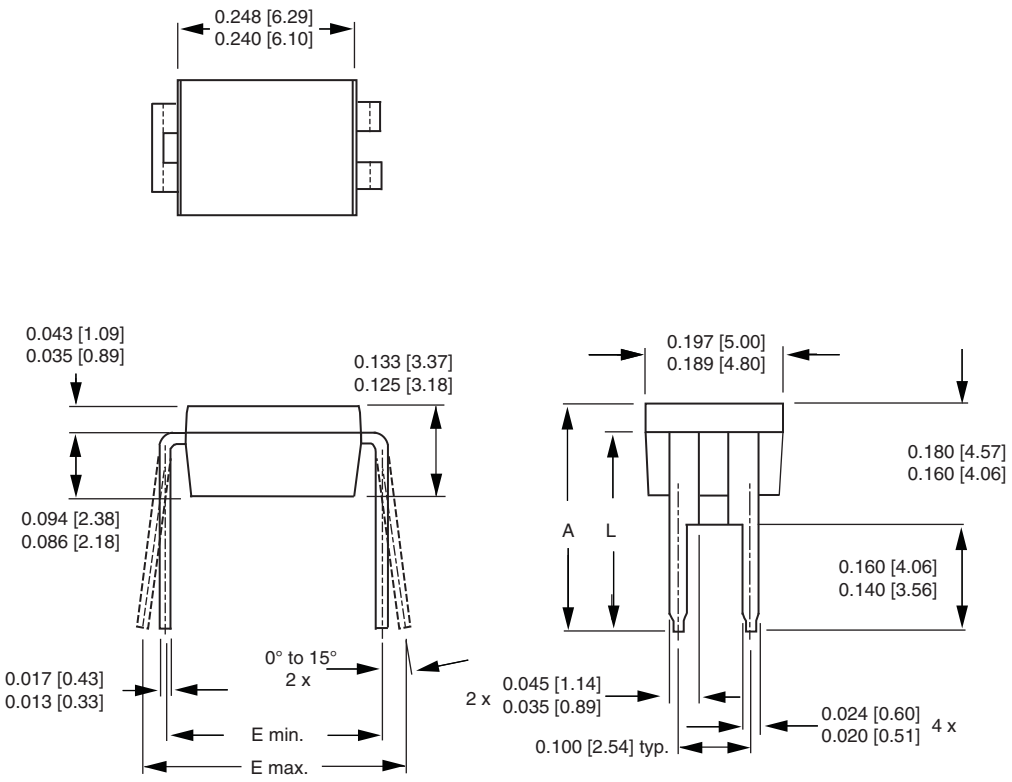
Note
• Compliment N-Channel of D.U.T. for driver



Note
a. V_{GS} = - 5 V for logic level and - 3 V drive devices

Fig. 14 - For P-Channel

HVM DIP (High voltage)



	INCHES		MILLIMETERS	
DIM.	**MIN.**	**MAX.**	**MIN.**	**MAX.**
A	0.310	0.330	7.87	8.38
E	0.300	0.425	7.62	10.79
L	0.270	0.290	6.86	7.36
ECN: X10-0386-Rev. B, 06-Sep-10 DWG: 5974				

Note

1. Package length does not include mold flash, protrusions or gate burrs. Package width does not include interlead flash or protrusions.

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